3GPP TSG-RAN WG2 Meeting #124 R2-2xxxxxx

Chicago, USA, Nov. 13th – 17th, 2023

Agenda: 8.8

Source: Session Chair (Intel)

Title: Report from IDC breakout session

Document for: Approval

**Organizational:**

* [AT124][700][IDC] Organizational Yi – IDC (Intel)

 Scope:

* Share plans for the meetings and list/status of ongoing email discussions for the sessions.
* Share meeting notes and agreements for review and endorsement.
* [AT124][701][IDC] Corrections on TS 38.331 Agreed in principle CR (Xiaomi)

 Scope: To discuss the changes from R2-2312128, R2-2313032, R2-2313335

 Intended outcome: Report in R2-2313701 and Updated TS 38,331 CR in R2-2313702

 **Deadline of company’ comments**: Wednesday 2023-11-15 2000

 **Deadline of comments on summary and the CR revision**: Thursday 2023-11-16 2000

## 7.10 IDC enhancements for NR and MR-DC

(NR\_IDC\_enh-Core; leading WG: RAN2; REL-18; WID: [RP-221281](http://ftp.3gpp.org/tsg_ran/TSG_RAN/TSGR_96/Docs/RP-221281.zip))

Time budget: 0 TU

Tdoc Limitation: 1 tdocs

Corrections. For smaller corrections please contact CR editor / Rapporteur directly.

### 7.10.1 In Principle Agreed CRs

In Principle Agreed CRs: 38.300 [Huawei], 38.331 [Xiaomi], 37.340 [ZTE], and capability CRs [Intel] should be updated based on the latest specifications.

R2-2312026 Introduction of Rel-18 IDC UE capabilities Intel Corporation CR Rel-18 38.306 17.6.0 0915 1 B NR\_IDC\_enh-Core R2-2305446

* Endorsed, to be merged into capability Mega CR

R2-2312027 Introcution of Rel-18 IDC UE capabilities Intel Corporation CR Rel-18 38.331 17.6.0 4106 1 B NR\_IDC\_enh-Core R2-2305447

* Endorsed, to be merged into capability Mega CR

R2-2313040 Introduction of In-Device Co-existence (IDC) enhancements for NR Huawei, HiSilicon CR Rel-18 38.300 17.6.0 0680 5 B NR\_IDC\_enh-Core R2-2311412

* Agreed

R2-2313559 Introduction of In-Device Co-existence (IDC) Enhancements for NR ZTE Corporation, Sanechips CR Rel-18 37.340 17.6.0 0367 2 B NR\_IDC\_enh-Core

* Agreed

R2-2313389 Introduction of In-Device Co-existence (IDC) enhancements for NR Xiaomi draftCR Rel-18 38.331 17.6.0 B NR\_IDC\_enh-Core

* To be treated in [AT124][701]
* [AT124][701][IDC] Corrections on TS 38.331 Agreed in principle CR (Xiaomi)

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R2-2313701 Summary of [AT124][701][IDC] Corrections on TS 38.331 Agreed in principle CR (Xiaomi) Xiaomi discussion Rel-18 NR\_IDC\_enh-Core

R2-2313702 Introduction of In-Device Co-existence (IDC) enhancements for NR Xiaomi CR Rel-18 38.331 17.6.0 4164 5 B NR\_IDC\_enh-Core

R2-2313331 37.340 running CR for introduction of IDC ZTE Corporation, Sanechips CR Rel-18 37.340 17.6.0 0374 - B NR\_IDC\_enh-Core

=> Withdrawn

### 7.10.2 Others

R2-2312128 Further corrections to RRC CR on IDC enhancements Lenovo discussion Rel-18 NR\_IDC\_enh-Core

* To be treated in [AT124][701]

R2-2313032 Corrections for 38.331 Running CR for IDC Enhancements Huawei, HiSilicon discussion Rel-18 NR\_IDC\_enh-Core

* To be treated in [AT124][701]

R2-2313335 Correction on the IDC Reporting ZTE Corporation, Sanechips discussion Rel-18 NR\_IDC\_enh-Core

* To be treated in [AT124][701]